

**Japanese Published Examined Patent Application (A) No. 02-290564, Published November 30, 1990; Application Filing No. 01-81982, Filed March 31, 1989; Int.: G01 R 1/073, H 01 L 21/66; Inventor(s): Tooru Ikeda et al.; Assignee: Tokyo Electron Corporation; Japanese Title: Probe Head and Method Therefor**

---

## **PROBE HEAD AND METHOD THEREFOR**

### **CLAIM(S)**

- 1) A method for manufacturing a probe head characterized by the following steps: when a probe is formed on an insulated substrate, the end of a wire is bonded by ultrasonic wave bonding to the predetermined position of the conductive pattern section on said insulated substrate; the wire is cut while being moved in the prescribed direction of the wire to form a whisker, which will constitute a probe.**
- 2) A probe head wherein a probe is installed on the insulated substrate, characterized in that a metal bump is formed at the predetermined position of the conductive pattern section on said insulated substrate, and this metal bump is used as a probe.**
- 3) A probe head, wherein a probe is installed on the insulated substrate, characterized in that a hard metal film is formed on the contact section of the probe that is to be contacted with an object to be measured.**
- 4) A probe head, wherein a probe is installed on the insulated substrate, characterized in that the insulated substrate is bonded to a base board with an adhesive via a number of particulate spacers.**